

Radiation hardness simulation of silicon thin detectors

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Outline

- Radiation damage modelling (F. Moscatelli)
- Thin structures (M. Petasecca)

Simulation Tool

Simulation tool:

–ISE-TCAD – discrete time and spatial solutions to equations

Damage modelling:

- Deep levels: N_t , E_t , σ_n and σ_p
- SRH statistics.
- Donor removal mechanism
- Other effects: high density defect concentration (clusters) produces an increase of the leakage current.

Radiation Damage Model

- **Four levels*:**
 - $V_2^{-/0}$ located at $E=E_C-0.42$
 - C_iO_i located at $E=E_V+0.36$
 - V_2O located at $E= E_C-0.50$
 - **E(70)** located at $E=E_C-0.45$
- **Direct charge exchange between $V_2^{-/0}$ and E(70) to reproduce cluster effects.**
- Donor removal mechanism.
- Reproduce variation of the V_{dep} and $I_{leakage}$ as a function of the fluence
- Over $\Phi=2\times 10^{14}$ n/cm² computational problems

*F. Moscatelli, et al. Nuclear Instruments and Methods in Physics Research B 186 (2002)

ISE-TCAD Damage Model

- **Three levels***:
 - $V_2^{-/0}$ located at $E=E_C-0.42$
 - C_iO_i located at $E=E_V+0.36$
 - V_2O located at $E= E_C-0.50$
- To reproduce cluster effects, we use increased $V_2^{-/0}$ occupancy
- **Donor removal mechanism.**

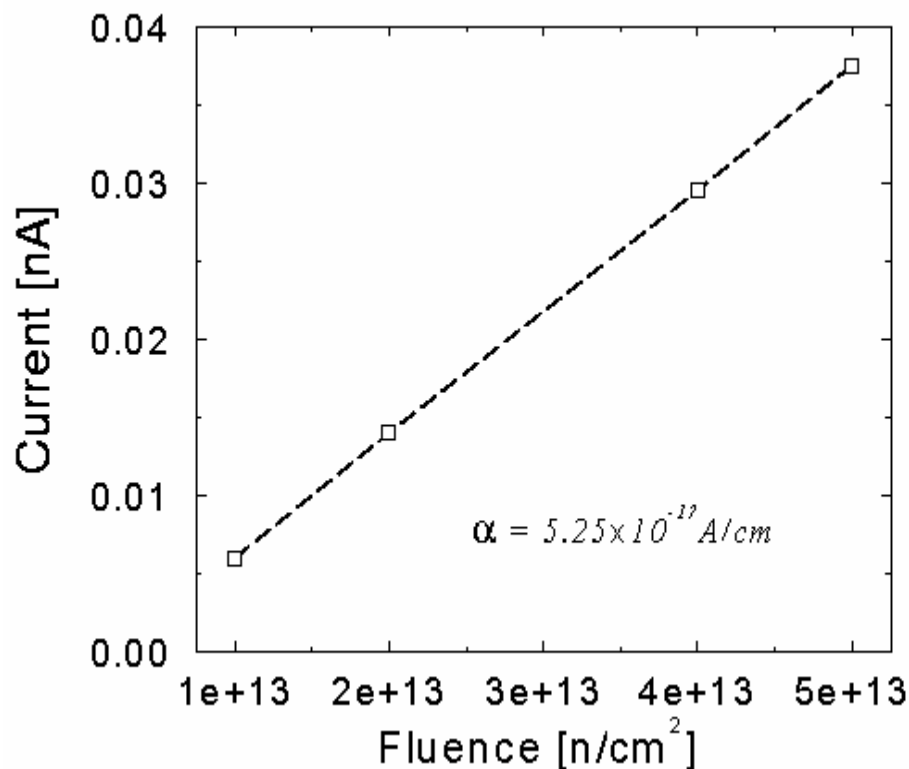
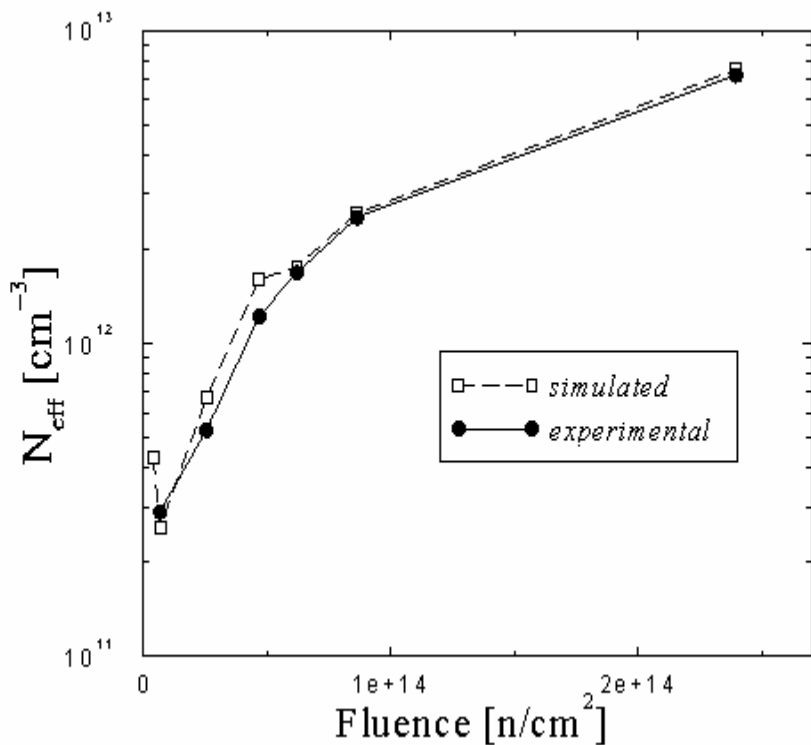
*D. Passeri, P. Ciampolini, G. Bilei and F. Moscatelli, *IEEE Trans. Nucl. Sci.*, vol. 48, pp. 1688, 2000

Three-level model

- Level characteristics:

	$V_2^{-/0}$	V_2O	C_iO_i
E	$E_c - 0.42eV$	$E_c - 0.50eV$	$E_v + 0.36eV$
σ_p	$8 \cdot 10^{-15} cm^2$	$10^{-15} cm^2$	$10^{-16} cm^2$
σ_n	$10^{-16} cm^2$	$10^{-16} cm^2$	$10^{-15} cm^2$
η	$26 cm^{-1}$	$0.1 cm^{-1}$	$1 cm^{-1}$

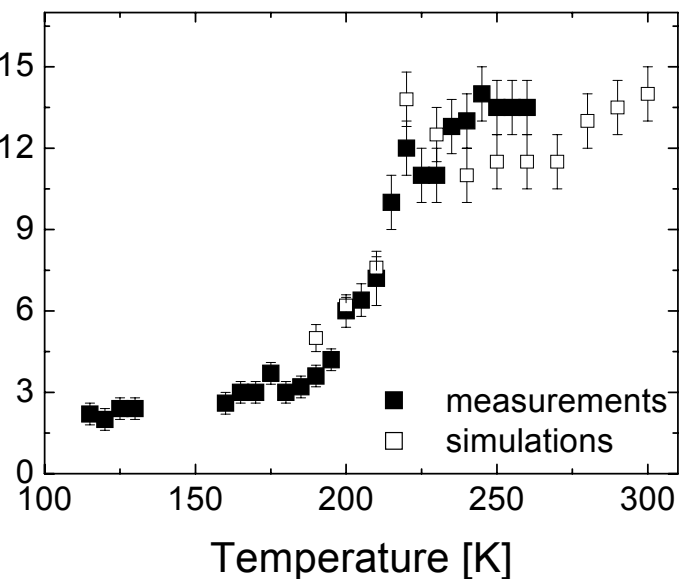
Effective Doping Concentration and Leakage Current



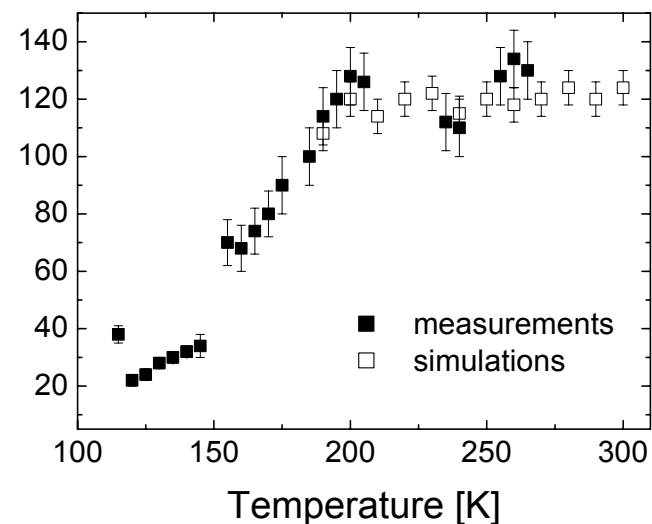
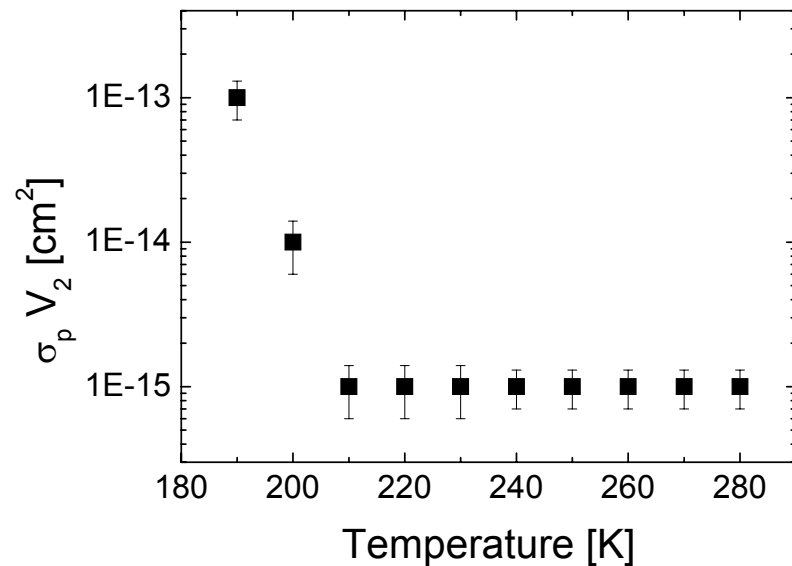
$\Delta I / \text{Volume} = \alpha \Phi$, with

 $\alpha = (2.9 \div 10) 10^{-17} \text{ A/cm}$.

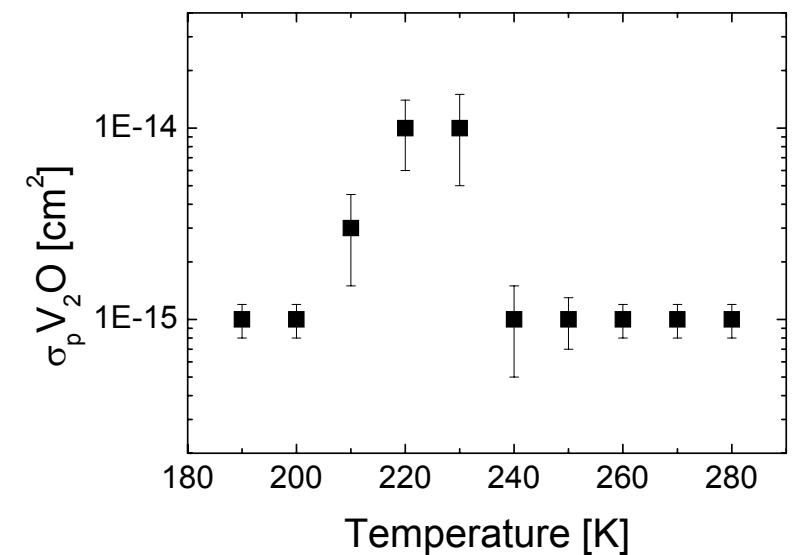
Simulations results as a function of T



$\Phi = 2.2 \times 10^{13}$ protons/cm²



$\Phi = 4.7 \times 10^{14}$ protons/cm²



Thin detectors

- Thin detectors have been proposed to investigate the possibility to get a low depletion voltage and to limit the leakage current of heavily irradiated silicon devices

Simulation setup

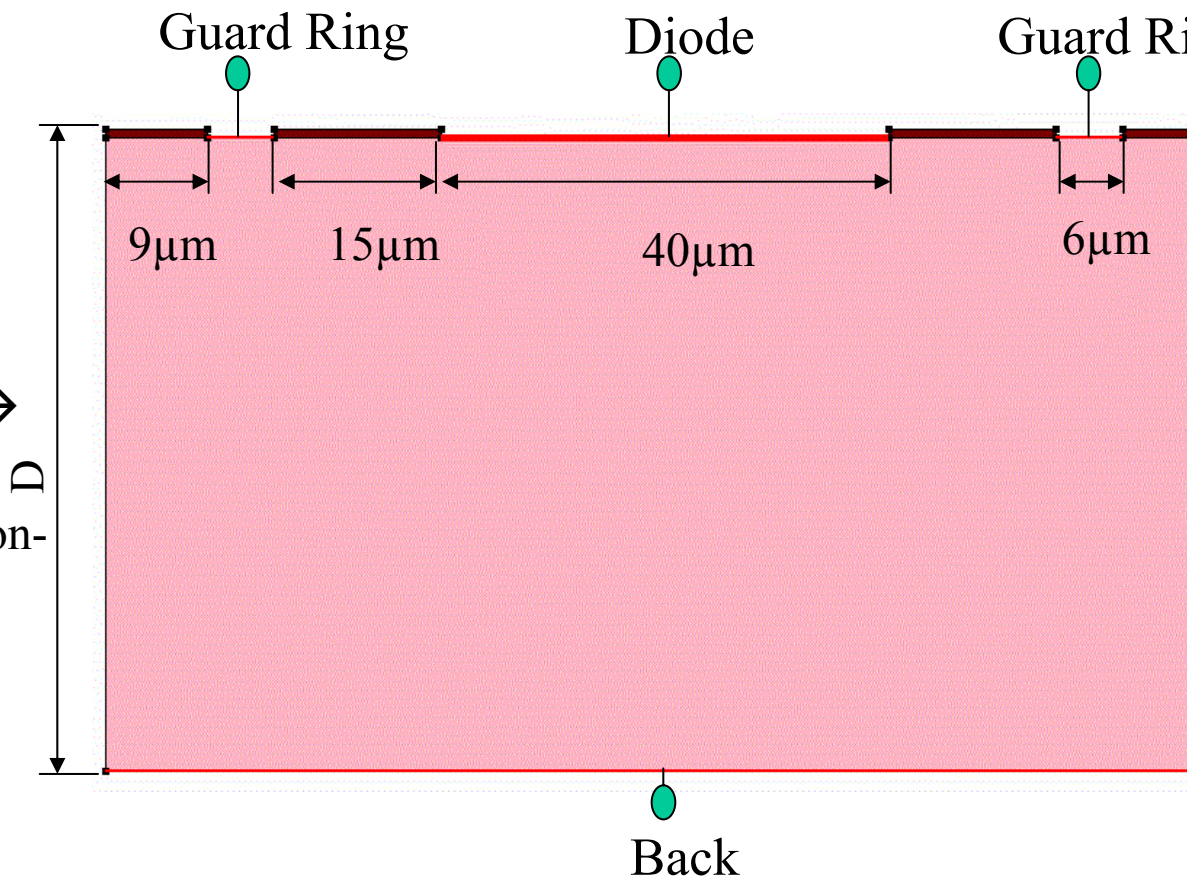
Simulated structures:

$$D = \begin{cases} 58 \mu\text{m} & \rightarrow \text{thin device} \\ 300 \mu\text{m} & \rightarrow \text{thick device} \end{cases}$$

Simulated device structure and parameters

Doping profiles:

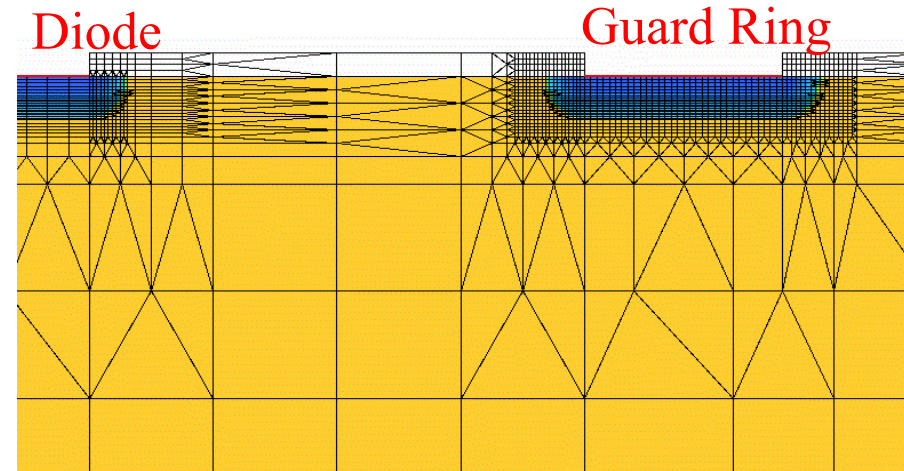
- n-doped substrate ($7 \times 10^{11} \text{ cm}^{-3}$) \rightarrow **6k Ω cm.**
- Charge concentration at the silicon-oxide interface of :
 - $4 \times 10^{11} \text{ cm}^{-3}$ pre-irradiation
 - $1 \times 10^{12} \text{ cm}^{-3}$ post-irradiation



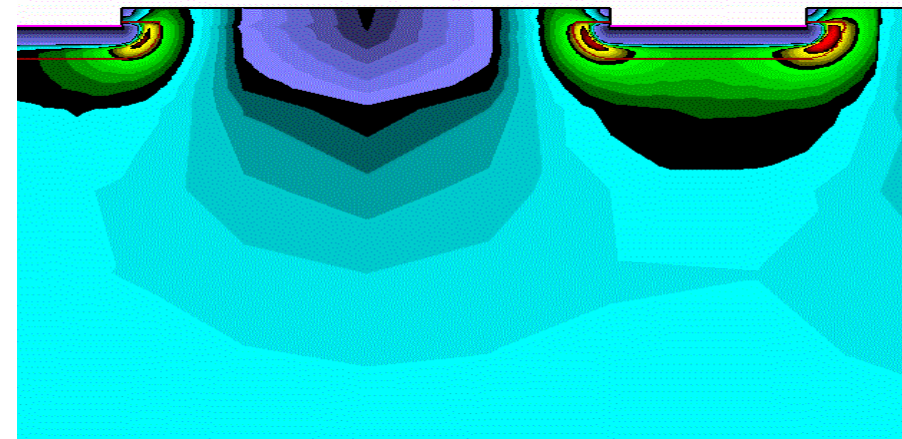
Simulation setup

Variable mesh definition:

- the mesh is better refined in correspondence of the **critical points** of the device to improve simulator performance.

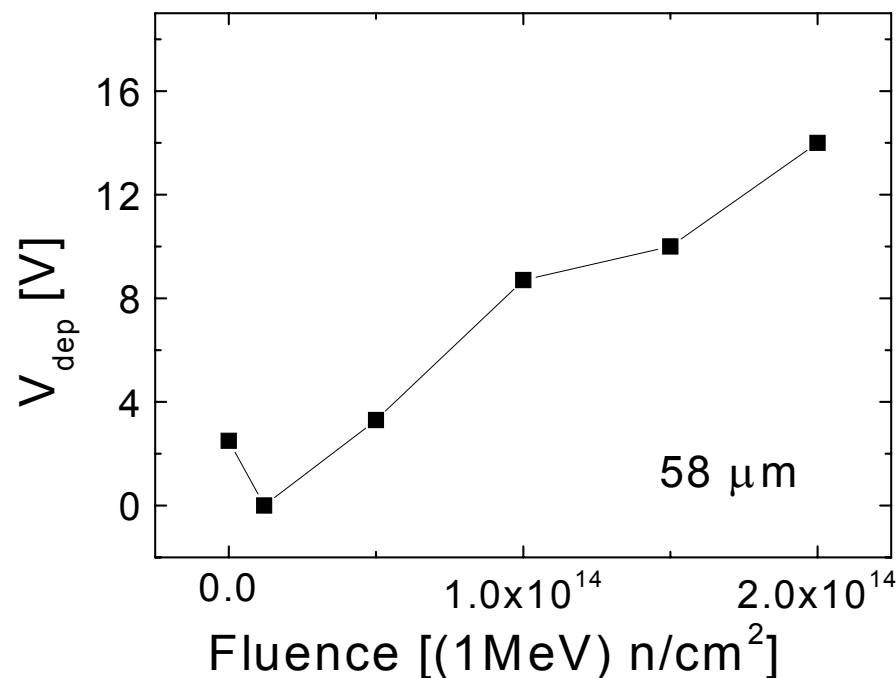
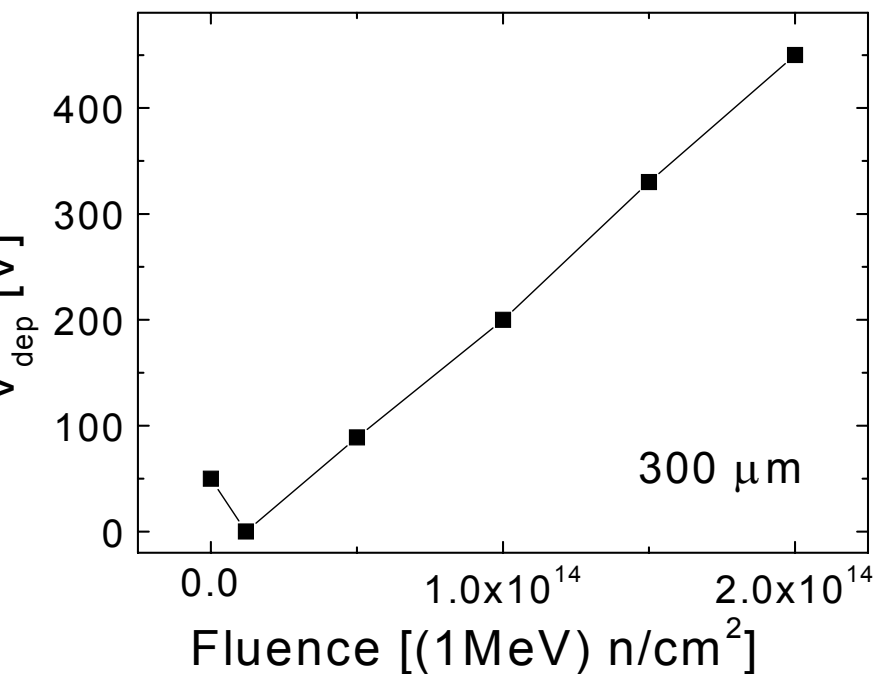


The typical electric field distribution at the full depletion voltage of the diodes: red areas correspond to the maximum



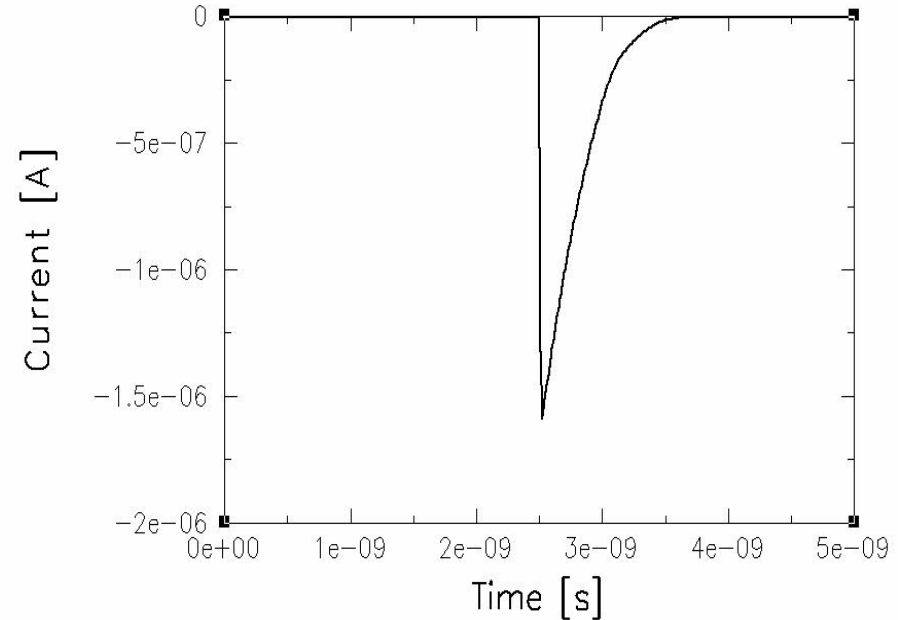
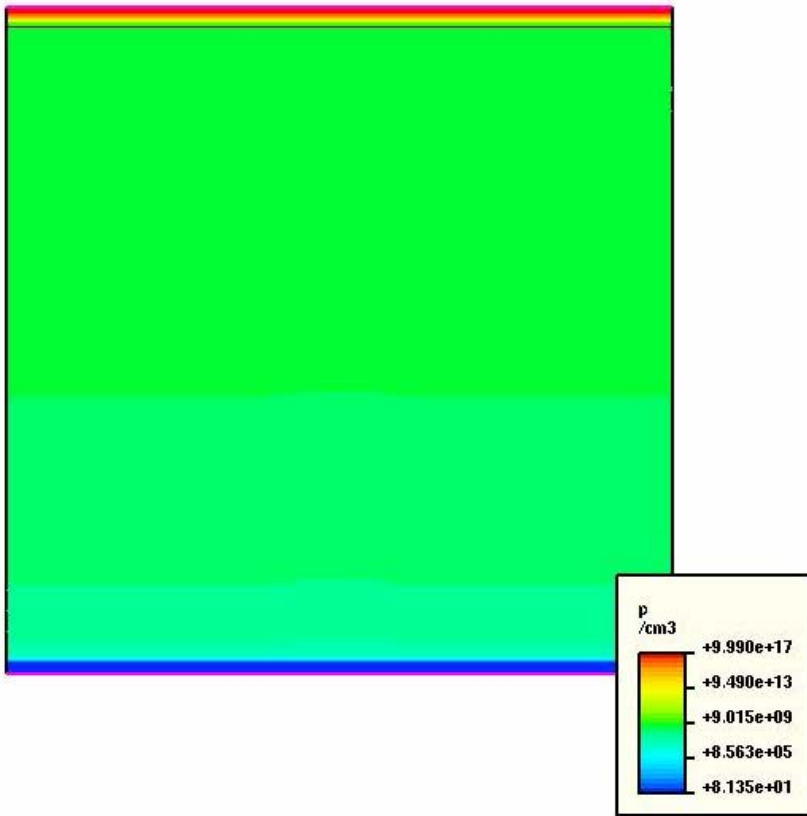
Simulation results

Simulated Depletion Voltage as function of the fluence



- V_{dep} in thin structures is one order of magnitude lower than in thick one
- V_{dep} of thin diode at a fluence of 1×10^{15} n/cm² is about 120 V while in thick diode is more than 3000 V !

CCE Simulation results

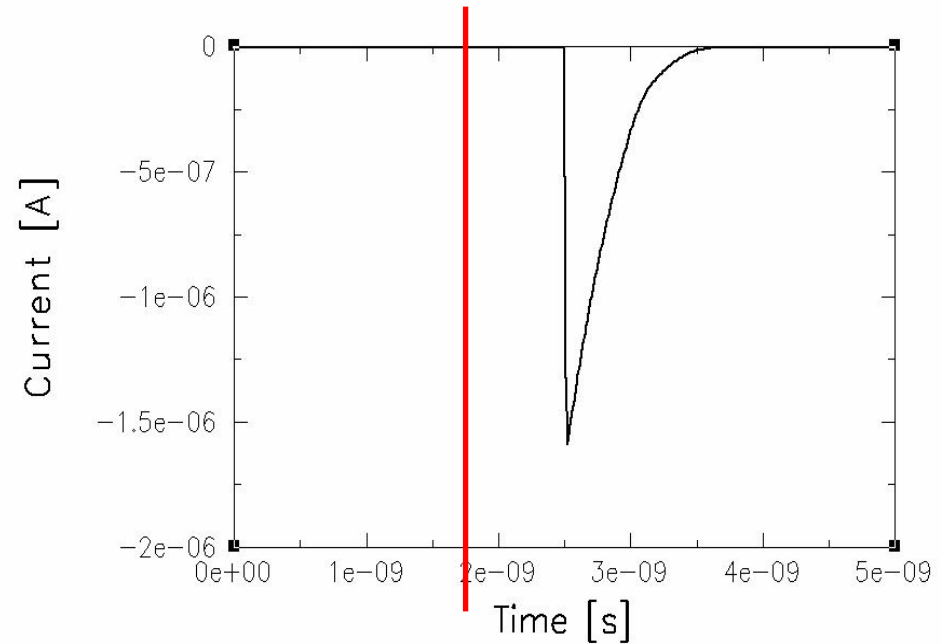
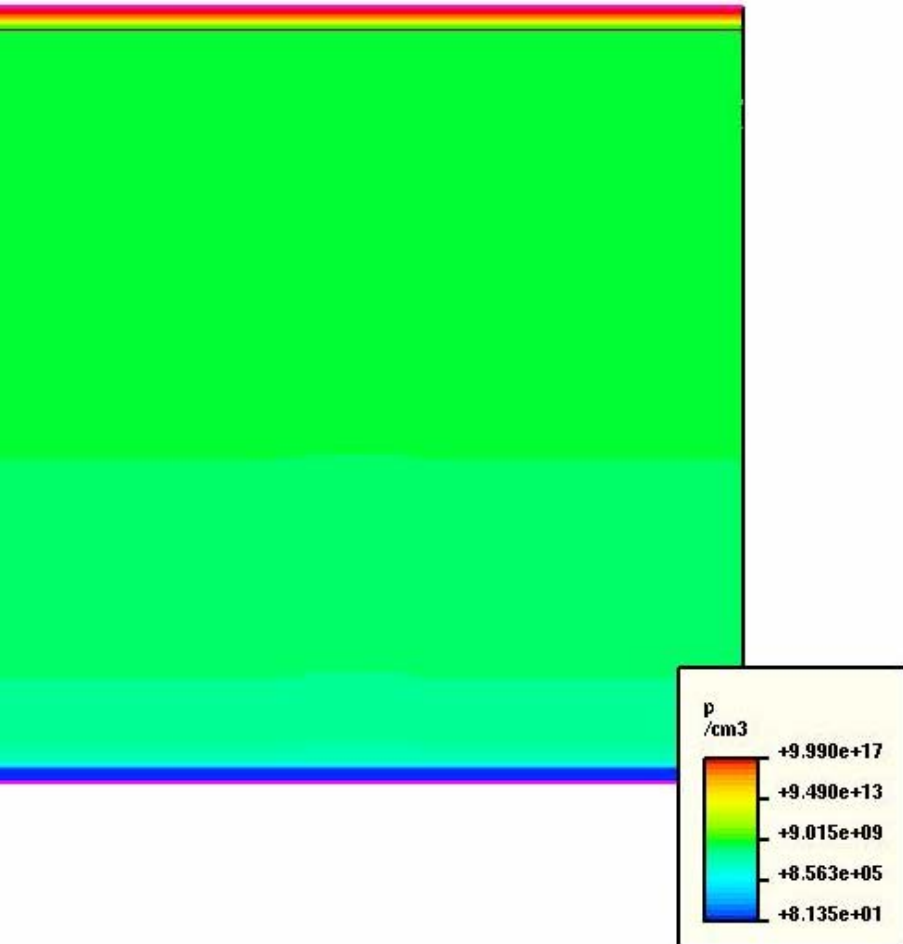


$$Q = \int I(t) dt$$

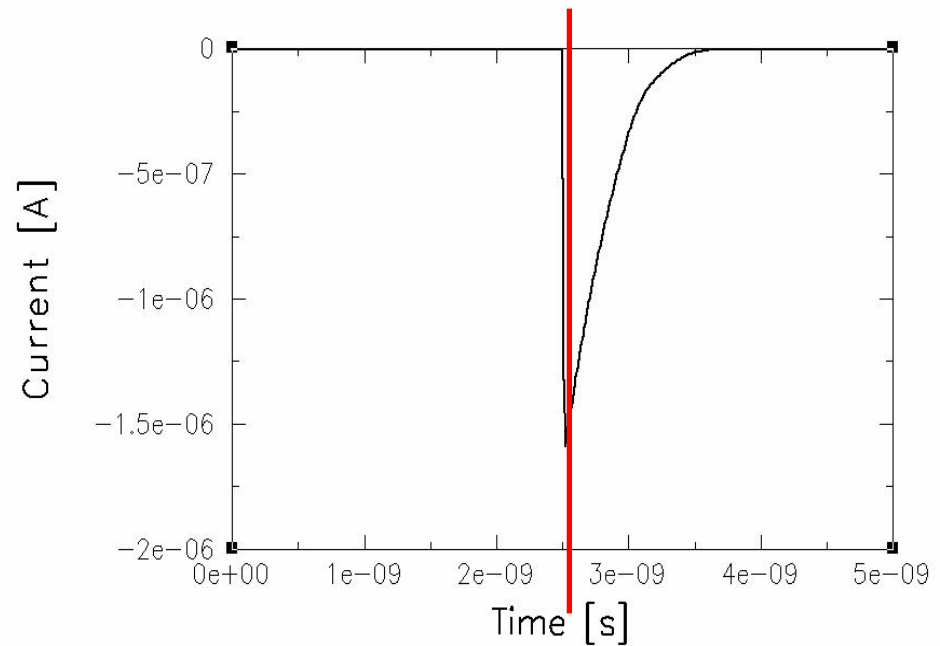
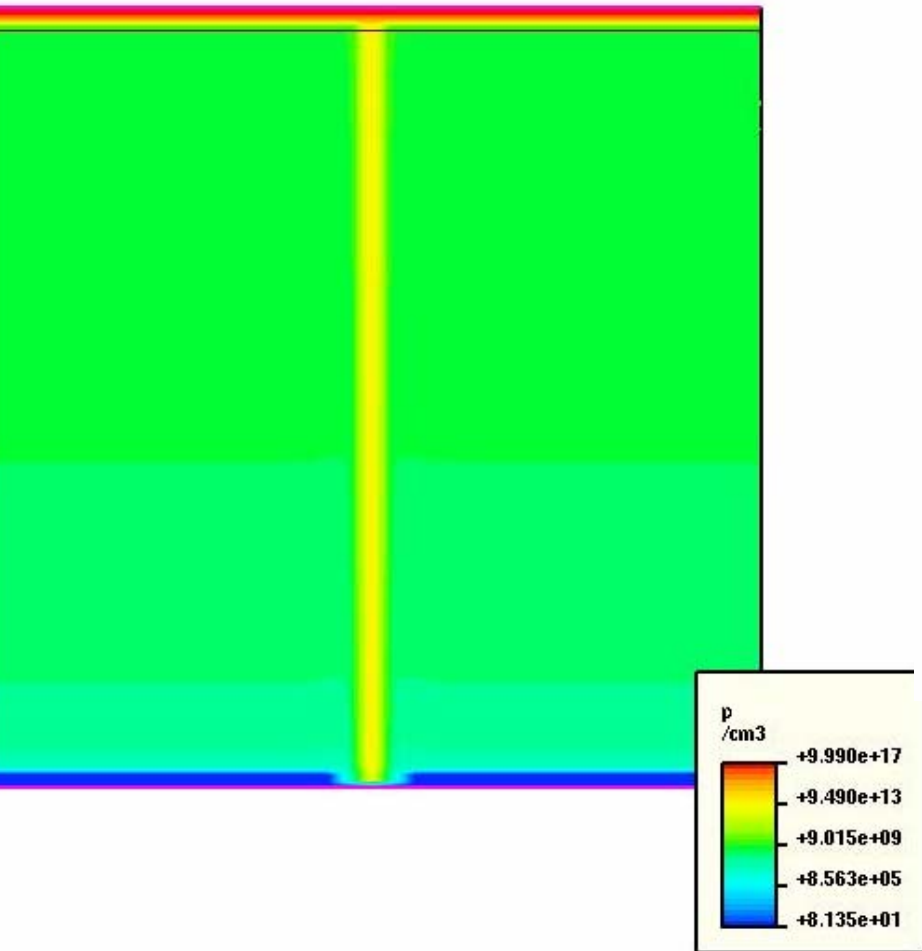
MIP: 80 e-h pairs/ μm

Cylinder diameter = $2\mu\text{m}$

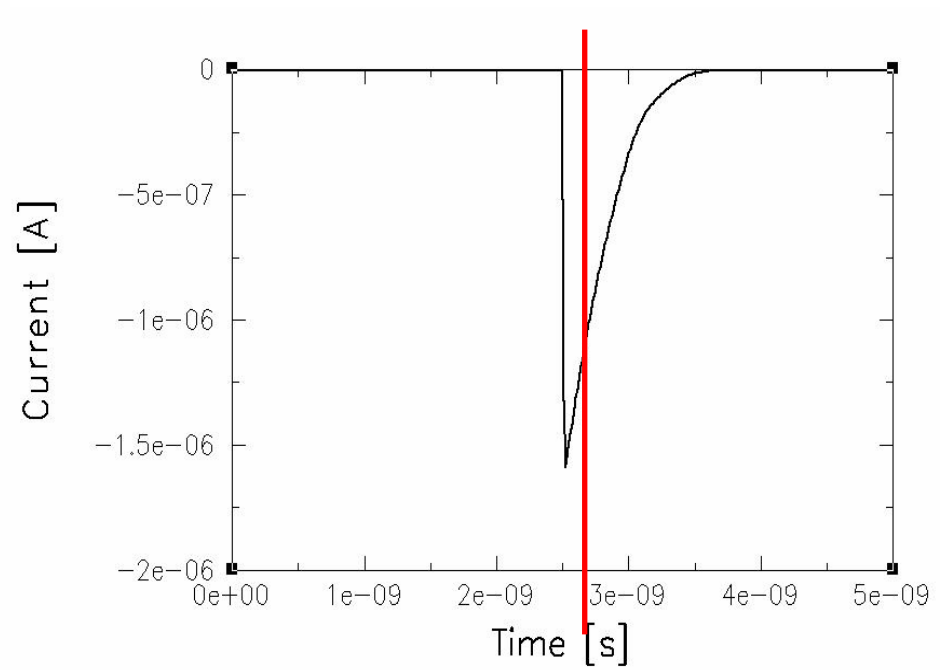
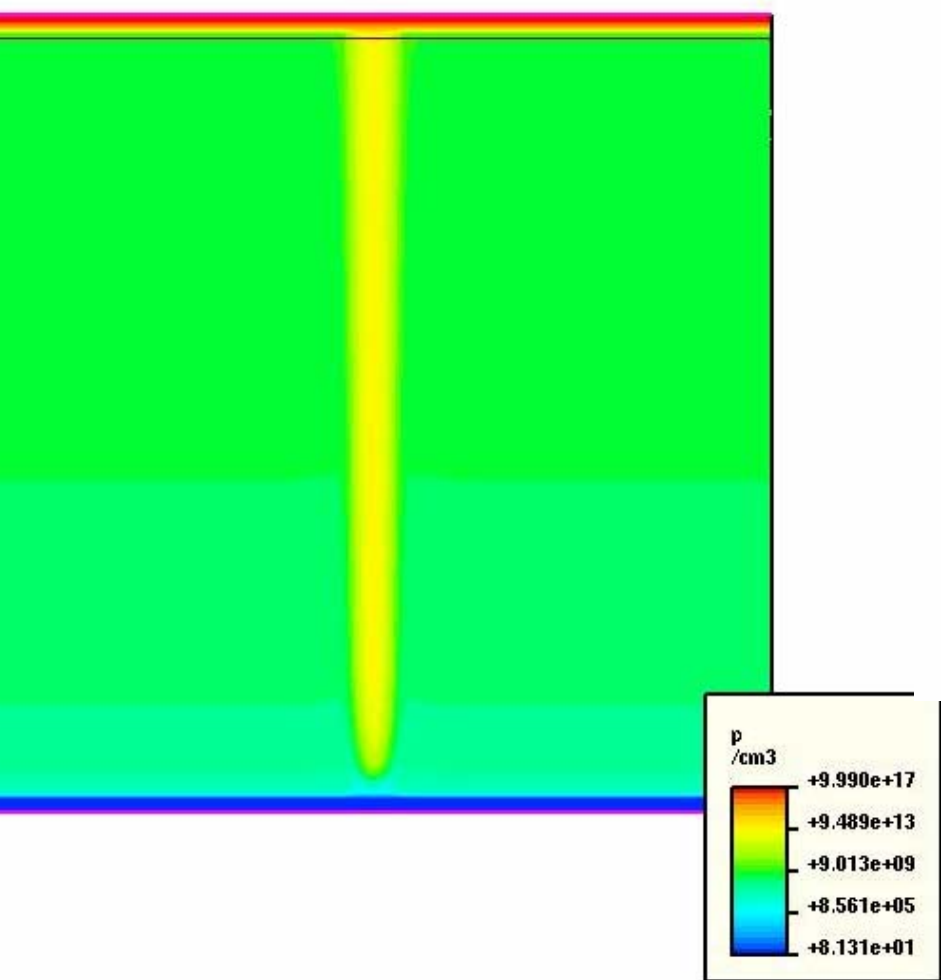
CCE Simulation results



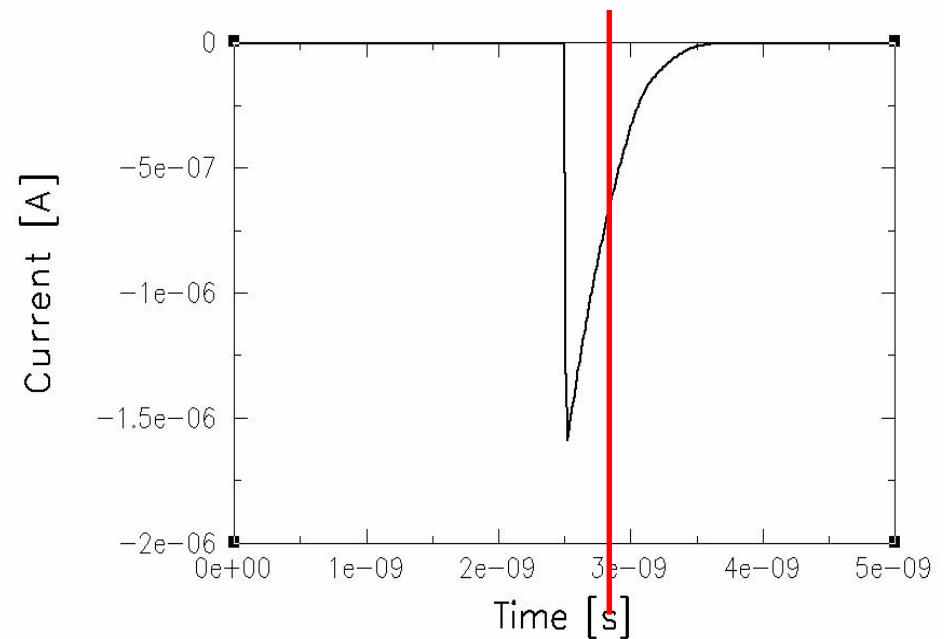
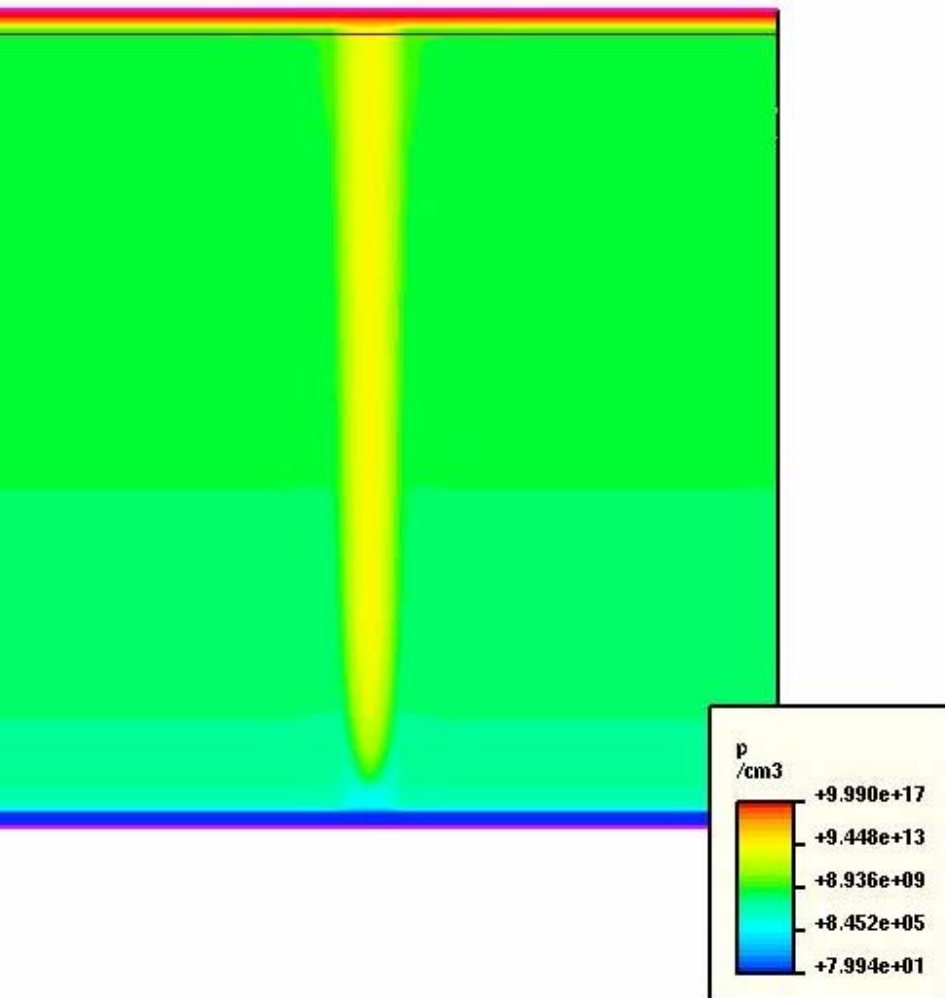
CCE Simulation results



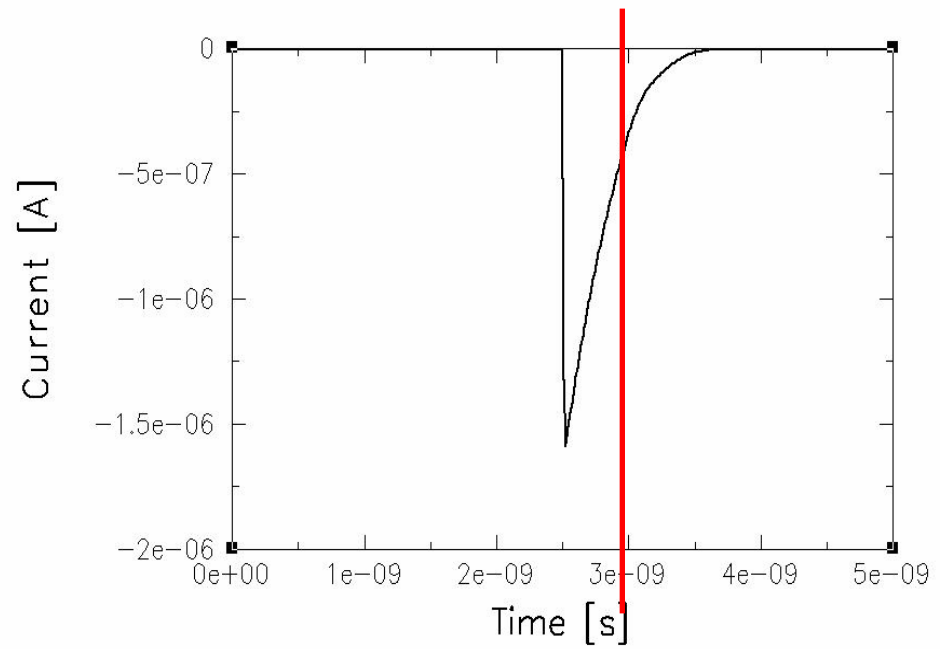
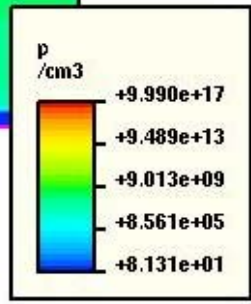
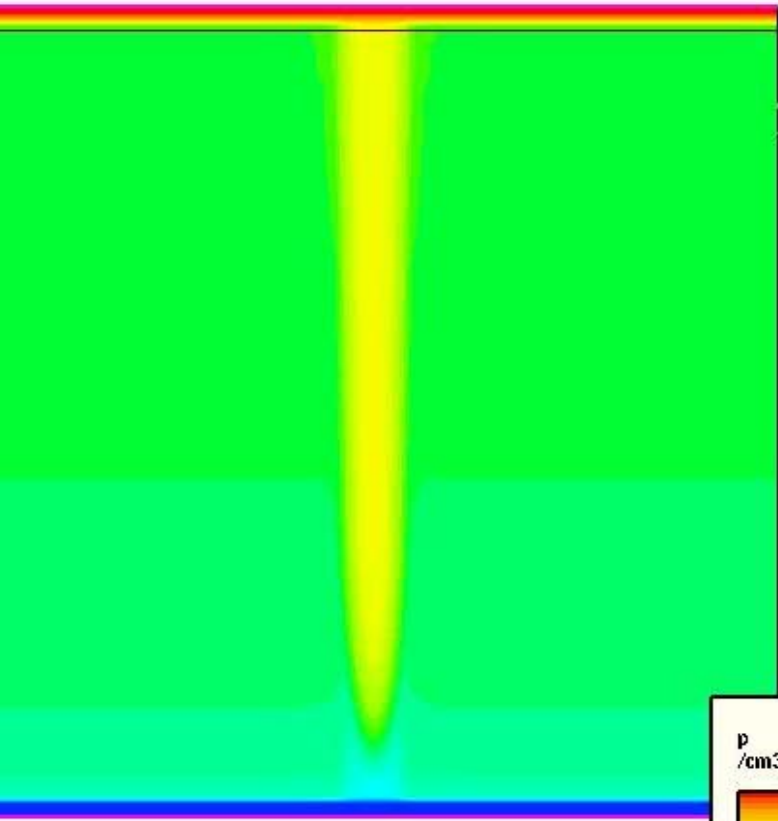
CCE Simulation results



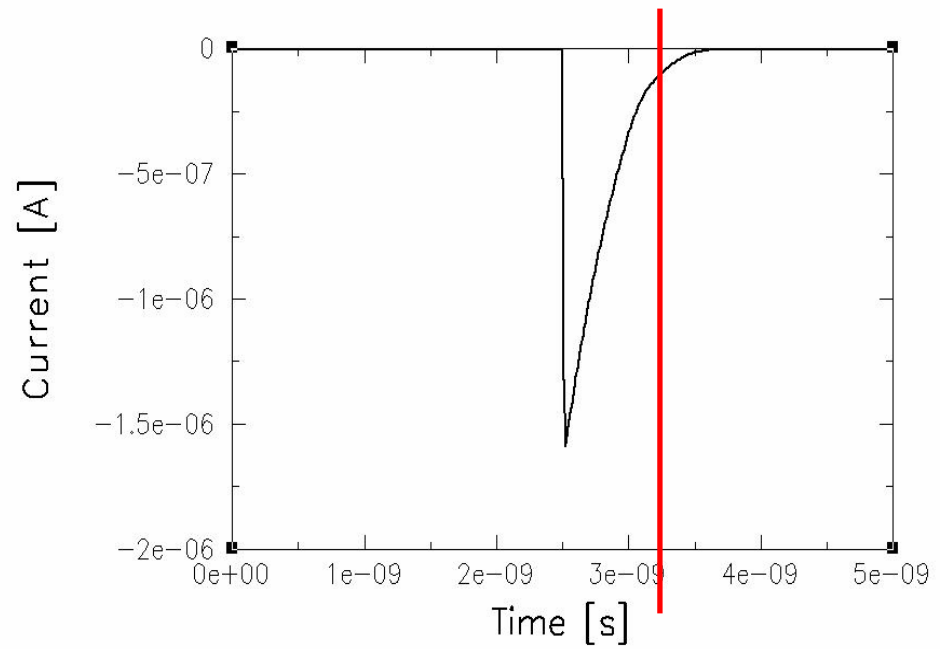
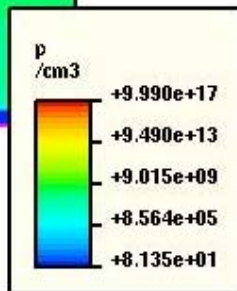
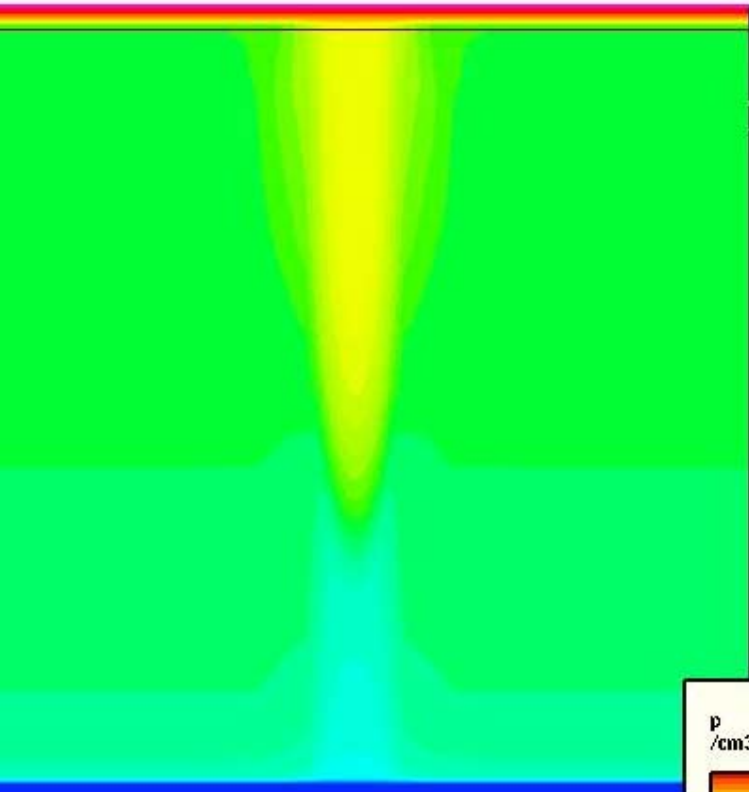
CCE Simulation results



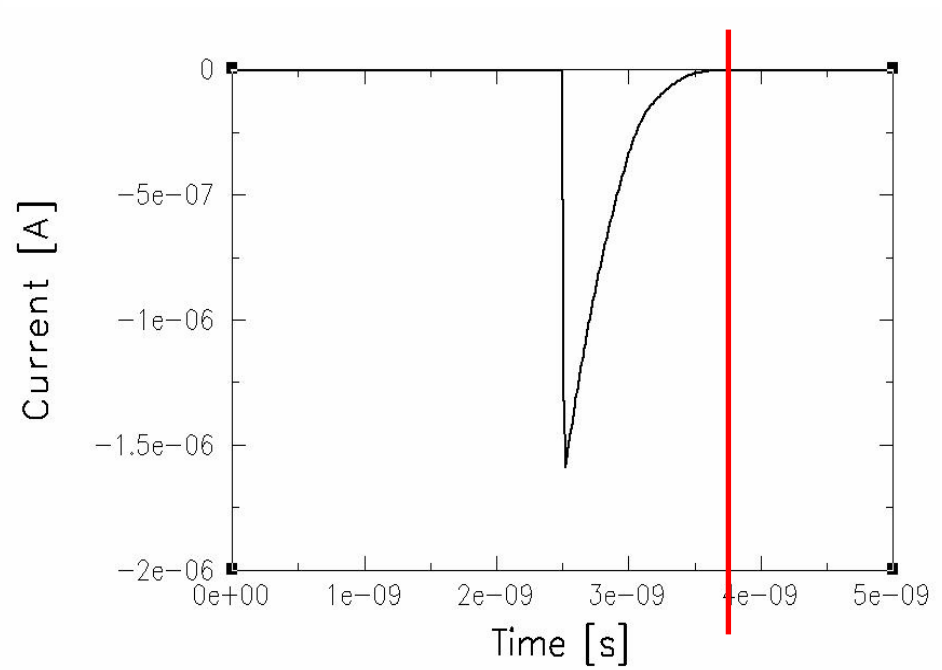
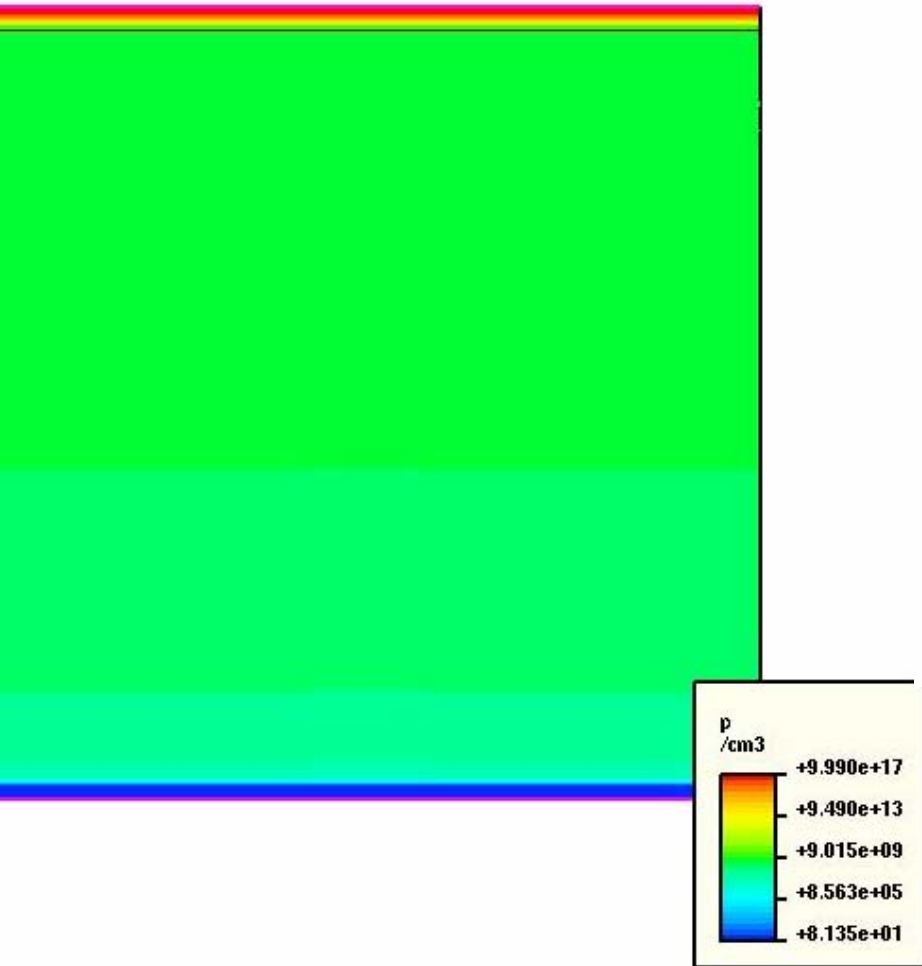
CCE Simulation results



CCE Simulation results



CCE Simulation results



Simulated CCE as function of the fluence

	Thick	Thin
$\Phi=2e14 \text{ n/cm}^2$	$Q_{@300V} = 1.6 \text{ fC}$	$Q_{@14V} = 0.58 \text{ fC}$
	CCE = 45%	CCE = 98%
	Exp. [1, 2] CCE = 42%	
$\Phi=1e15 \text{ n/cm}^2$	$Q_{@VBD=300V} = 1 \text{ fC}$	$Q_{@120V} = 0.57 \text{ fC}$
	CCE = 27%	CCE = 95%
	Exp.CCE = 20-30%	

For $\Phi=1e15 \text{ n/cm}^2$

$$Q_{\text{thin}} = 57\% Q_{\text{thick}}$$

Thin @ 120V NO Breakdown risk and full depleted

- [1] L.Beattie et al./
NIM 412A (98)
- [2] M.Bruzzo et al./
NIM 61B(98)

Conclusions

Irradiated thin and thick diodes have been analyzed considering a three levels simulation model until $\Phi=1e15$ n/cm²

Thin features:

- V_{dep} in thin structures is one order of magnitude lower
- CCE at very high fluence (10^{15} n/cm²) is 95% for the thin structures.
- $Q_{thin} = 57\% Q_{thick}$

Next step is to simulate thin structures at higher fluences ($1e16$ n/cm²) and measure irradiated ones.